

ABSTRACT

An assembly and method for manufacturing individual microelectronic devices, such as surface acoustic wave devices, employs a unitary array of a nonconductive material having plural spaced cavities extending into the array, with a recess at each cavity dimensioned to receive a lid which is sealed therein. Conductive paths are provided from the interior of each cavity to a surface of the array, in order to make electrical contact with a component hermetically sealed within the cavity.